2SD1539A

Silicon NPN epitaxial planar type

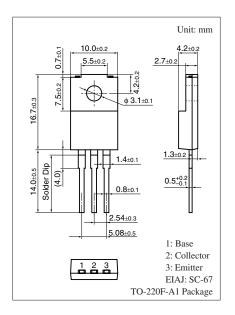
For low-voltage switching Complementary to 2SB1071A

■ Features

- Low collector-emitter saturation voltage V_{CE(sat)}
- High-speed switching
- Full-pack package which can be installed to the heat sink with one screw

■ Absolute Maximum Ratings $T_C = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (En	V_{CBO}	50	V	
Collector-emitter voltage	V _{CEO}	40	V	
Emitter-base voltage (Col	V _{EBO}	5	V	
Collector current	I_{C}	4	A	
Peak collector current	I_{CP}	8	A	
Collector power	P _C	25	W	
dissipation	$T_a = 25$ °C		2.0	
Junction temperature	T _j	150	°C	
Storage temperature	T_{stg}	-55 to +150	°C	



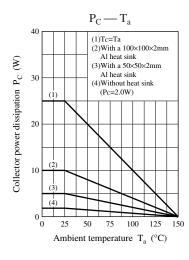
■ Electrical Characteristics $T_C = 25$ °C ± 3 °C

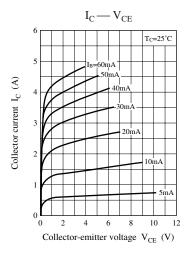
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V _{CEO}	$I_C = 10 \text{ mA}, I_B = 0$	40			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 50 \text{ V}, I_{E} = 0$			50	μΑ
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = 5 \text{ V}, I_{C} = 0$			50	μΑ
Forward current transfer ratio	h _{FE1}	$V_{CE} = 2 \text{ V}, I_{C} = 0.1 \text{ A}$	45			_
	h _{FE2} *	$V_{CE} = 2 \text{ V}, I_{C} = 1 \text{ A}$	60		260	
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 2 A, I_B = 0.1 A$			0.5	V
Base-emitter saturation voltage	V _{BE(sat)}	$I_C = 2 A, I_B = 0.1 A$			1.5	V
Transition frequency	f_T	$V_{CE} = 5 \text{ V}, I_{C} = 0.5 \text{ A}, f = 10 \text{ MHz}$		120		MHz
Turn-on time	t _{on}	$I_C = 2 A$, $I_{B1} = 0.2 A$, $I_{B2} = -0.2 A$		0.2		μs
Storage time	t _{stg}	$V_{CC} = 20 \text{ V}$		0.5		μs
Fall time	t_{f}			0.1		μs

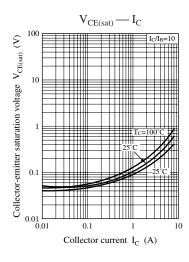
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

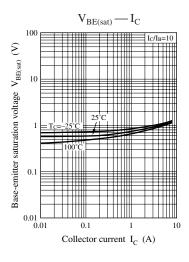
2. *: Rank classification

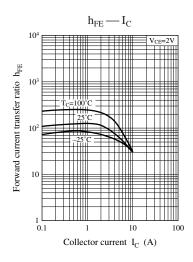
Rank	R	Q	P	
h _{FE2}	60 to 120	90 to 180	130 to 260	

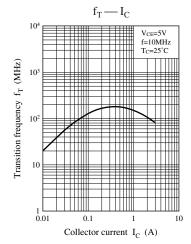


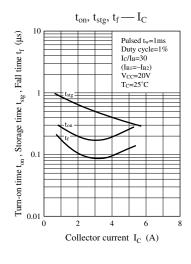


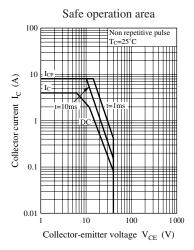


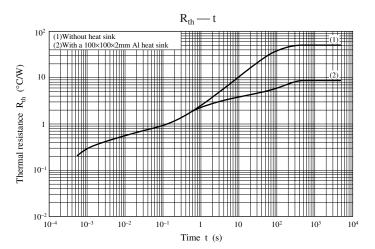












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